

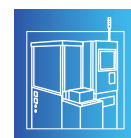


# DICING SAWS



Range & Solutions

## Full Dicing Solutions



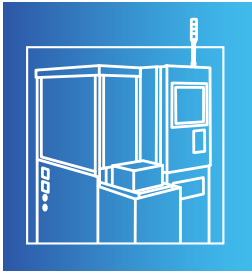
Saws



Blades



Peripherals



## ADT DICING SAWS

ADT's dicing saws' line offer a variety of capabilities, configurations and levels of automation as well as unique solutions for special materials and applications. The dicing saws range includes automatic saws, fully automatic saws with single and double spindle, as well as special machines for tailored applications.



Scan to see  
our image  
video

### ADT'S DICING SAWS UNIQUE FEATURES

#### Advantages

- Low cost of owner ship
- High throughput
- User freindly
- Flexible
- Customization

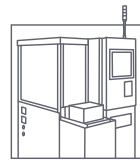
#### Monitoring

- Temperature monitoring
- Water Flow Monitoring
- Kerf Monitoring
- Product mapping - confocal

#### Reliability

- Spindle air reservoir
- UPS – Cut Map Saving
- Broken Blade Detector
- Geometric model finder
- Enhanced Kerf check inspection
- Vibration Dampers
- X Air bearing Axis

### Quality Standards



## Dicing Saws | Fully Automatic

# FULLY AUTOMATIC TWIN SPINDLE DICING SAWS

## 8030

12" Silicon wafer dicing supporting 6" and 8" wafers plus Large QFN multi panels



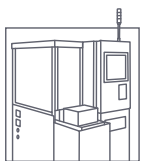
### Features & Benefits

- Up to 76.2mm (3") Blades OD
- Support up to 12" X 12" chuck
- Ionizer Bar – ESD discharge
- BARCODE item identification
- SECS GEM ready

<b>Workpiece Size</b>	Ø 8", Ø 12" or 12" x 12" square	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm	
<b>Blade Size</b>	2" – 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Z1 / Z2 Axis</b>	Max. Stroke	50 mm (for 2.188" blade OD)
	Resolution	0.2 µm
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Spinning speed	Full rinse and dry cycle 100-3,000 rpm
	Cleaning Method	Atomized cleaning capabilities
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	1145 x 1687 x 1830
	Weight	1,500kg

### Materials:

Silicon wafers | Thin Glass | QFN and BGA multi pannels



# FULLY AUTOMATIC TWIN SPINDLE DICING SAWS

## 8020

8" silicon wafer dicing saw or other material such as Glass, SiC and more



### Features & Benefits

- Flexibility – Supports Hub and Hubless blades up to 3" O.D.
- Spindles of 1.8 kW or 2.2 kW high power
- Intuitive operation interface using a large 19" touch screen monitor
- Fast & simple blade change
- SECS / GEM platform ready

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm	
<b>Blade Size</b>	2" – 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
	Cutting Range	210 mm
<b>X Axis</b>	Air Slide	
<b>Z1 / Z2 Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	30 mm (for 2.188" blade OD)
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Full rinse and dry cycle	
	Spinning speed	100-3,000 rpm
	Cleaning Method	Atomized cleaning capabilities
<b>Utilities</b>	Electrical	
		200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	1820 x 1460 x 1015
	Weight	1,300kg

### Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) MEMS | SAW devices | Glass wafer | Packaging (QFN, LED...)

## 80WT

For Wettable Flank Process



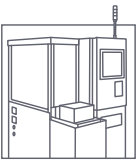
### Features & Benefits

- Designed for precise Shallow cut Wettable QFN dicing. The 80WT performs perfect grooving operation with constant depth of cut and groove shape, on an uneven surface of the substrate
- Confocal sensor
- Loading up to 4 QFN magazines Tapeless process
- Automatic loading 2 QFN panels (can support single panel)
- Brush deburring

<b>Workpiece Size</b>	up to 12" X 12" Square	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm	
<b>Confocal sensor</b>	Accuracy ±15 µm	
<b>Blade Size</b>	2" – 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
	Cutting Range	350 mm
<b>X Axis</b>	Air Slide	
<b>Z1 / Z2 Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	50 mm (for 2.188" blade OD)
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Full rinse and dry cycle	
	Spinning speed	100-3,000 rpm
	Cleaning Method	Atomized cleaning capabilities
<b>Utilities</b>	Electrical	
		200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	1145 x 1687 x 1830
	Weight	1,500kg

### Materials:

QFN



# FULLY AUTOMATIC SINGLE SPINDLE DICING SAWS

## 7222

### 2" Spindle

8" silicon wafer dicing saw or other material such as PZT, IR glass and more



#### Features & Benefits

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	60K rpm / 1.8 kW or 2.2KW	
<b>Blade Size</b>	2" – 3"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Spinning speed	Full rinse and dry cycle 100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
	<b>Utilities</b>	Electrical
<b>Dimensions</b>	(W x D x H) mm	965 X 1460 X 1700
	Weight	1,200kg

#### Materials:

Silicon | Glass on Silicon | MEMS | GaAs wafers | Package Singulation (BGA & QFN) | LTCC | PCB | Hard Materials

## 7302

### 2" Spindle

For silicon / glass wafers



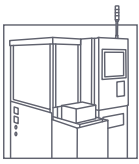
#### Features & Benefits

- Internal air flow management management minimizing product contamination
- Multi panel dicing
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Custom process solution
- UV LED curing system
- Broken Blade detector (for 2" spindle)
- Exhaust impeller
- High power 2" spindle up to 2.2KW
- Height Measuring Tool (HMT)
- SECS GEM communication protocol

<b>Workpiece Size</b>	Ø 12" or 9" X 12"	
<b>Spindle</b>	60K rpm / 1.8 kW or 2.2KW	
<b>Blade Size</b>	2" - 3"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
	Cutting Range	350 mm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	50 mm (for 2.188" blade OD)
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Spinning speed	Full rinse and dry cycle 100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
	<b>Utilities</b>	Electrical
<b>Dimensions</b>	(W x D x H) mm	1100 x 1785 x 1700
	Weight	1,350kg

#### Materials:

Silicon Wafers | PCB | QFN and BGA multi panels | LED Packages



# FULLY AUTOMATIC SINGLE SPINDLE DICING SAWS

## 7224

### 4" Spindle

Hard material dicing such as glass and ceramic



#### Features & Benefits

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results



<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	30K rpm / 2.5 kW	
<b>Blade Size</b>	4" - 5"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Spinning speed	Full rinse and dry cycle 100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
	Utilities	Electrical
<b>Dimensions</b>	(W x D x H) mm	965 x 1460 x 1700
	Weight	1,200kg

#### Materials:

Glass on Silicon | MEMS | Package Singulation (BGA & QFN) | LTCC | PCB | Hard Materials

## 7304

### 4" Spindle

Hard material dicing such as glass and ceramic



#### Features & Benefits

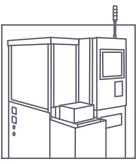
- Support 4"-5" blade O.D.
- Internal air flow management minimizing product contamination
- Multi panel dicing
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Custom process solution
- UV LED curing system
- Exhaust impeller
- Height Measuring Tool (HMT)
- Bar code reader (Internal or external)
- SECS GEM communication protocol



<b>Workpiece Size</b>	9" X 12"	
<b>Spindle</b>	30K rpm / 2.5 kW	
<b>Blade Size</b>	4" - 5"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Cleaning Station</b>	Spinning speed	Full rinse and dry cycle 100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
	Utilities	Electrical
<b>Dimensions</b>	(W x D x H) mm	1100 x 1785 x 1700
	Weight	1,350kg

#### Materials:

Glass | Ceramc | PZT | PCB | Alumina | More



# AUTOMATIC TWIN SPINDLE DICING SAWS

## 7900 Duo

For 8" silicon and GaAs wafers



## 7920 Duo

Multi panel for dicing glass, saw devices and other application



### Features & Benefits

- Up to 8"x 8" products
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm	
<b>Blade Size</b>	2" - 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z1 / Z2 Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	30 mm (for 2.188" blade OD)
<b>Θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	875 X 975 X 1450
	Weight	900 kg

### Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) | MEMS | SAW devices | Glass wafer | Packaging (QFN, LED...)

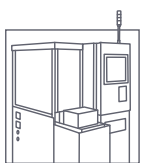
### Features & Benefits

- Up to 10" X 10" chuck
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

<b>Workpiece Size</b>	10" x 10"	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm	
<b>Blade Size</b>	2" - 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z1 / Z2 Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	30 mm (for 2.188" blade OD)
<b>Θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	875 X 975 X 1450
	Weight	900 kg

### Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) | MEMS | SAW devices | Glass wafer | Packaging (QFN, LED...)



## AUTOMATIC TWIN SPINDLE DICING SAWS

### 7930 Duo

For high UPH for large and multi panels



#### Features & Benefits

- Up to 12" X 10" chuck
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

<b>Workpiece Size</b>	12" x 10" or Ø 12"	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm	
<b>Blade Size</b>	2" - 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z1 / Z2 Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
	Max. Stroke	30 mm (for 2.188" blade OD)
<b>Θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	875 X 975 X 1450
	Weight	900 kg

#### Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) | MEMS | SAW devices | Glass wafer | Packaging (QFN, LED...)

## AUTOMATIC SINGLE SPINDLE DICING SAWS

### 7122

2" Spindle

Most flexible system



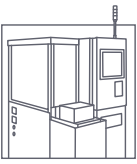
#### Features & Benefits

- Support 2"-3" blade O.D.
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution
- Fast & simple blade change with a locking spindle shaft

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	60K rpm / 1.8 kW or 2.2KW	
<b>Blade Size</b>	2" - 3"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	965 x 1300 x 1600
	Weight	900 kg

#### Materials:

Glass | PZT | LED & LED on PCB Packages | Sensors & MEMS | Opto-electronic Components | IC Wafers | Automotive Sensors | Ceramic Substrates & Capacitors | Glass on Silicon | LTCC | SAW Filters | Package Singulation (BGA, QFN)



# AUTOMATIC SINGLE SPINDLE DICING SAWS

## 7132

### 2" Spindle

Suitable for large variety of products



#### Features & Benefits

- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

<b>Workpiece Size</b>	Ø 12" or 300mm X 300mm W/O frame	
<b>Spindle</b>	60K rpm / 1.8 kW or 2.2KW	
<b>Blade Size</b>	2" – 3"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	965 x 1300 x 1600
	Weight	900 kg

#### Materials:

Glass | PZT | LED & LED on PCB Packages | Sensors & MEMS | Opto-electronic Components | IC Wafers | Automotive Sensors  
Ceramic Substrates & Capacitors | Glass on Silicon | LTCC | SAW Filters | Package Singulation (BGA, QFN)

## 7124

### 4" Spindle

For thick and hard material



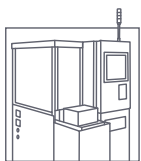
#### Features & Benefits

- Support 4"-5" blade O.D. with large 'Z' stroke
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Custom process solution

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	30K rpm / 2.5 kW	
<b>Blade Size</b>	4" – 5"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	965 x 1300 x 1600
	Weight	900 kg

#### Materials:

Glass | PZT | LED & LED on PCB Packages | Opto-electronic Components | Automotive Sensors  
Ceramic Substrates & Capacitors | LTCC | SAW Filters | Package Singulation (BGA, QFN)



## AUTOMATIC SINGLE SPINDLE DICING SAWS

### 7134

#### 4" Spindle

Support 12" square and thick products



#### Features & Benefits

- Support 4"-5" blade O.D.
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

<b>Workpiece Size</b>	Ø 12" or 300mm X 300 mm W/O frame	
<b>Spindle</b>	30K rpm / 2.5 kW	
<b>Blade Size</b>	4" – 5"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	965 x 1300 x 1600
	Weight	900 kg

#### Materials:

Glass | PZT | LED & LED on PCB Packages | Opto-electronic Components | IC Wafers | Automotive Sensors  
Ceramic Substrates & Capacitors | Glass on Silicon | LTCC | SAW Filters | Package Singulation (BGA, QFN)

## UNIQUE SOLUTIONS

### 71TS

For fiber optic and waveguides



- Will support standard dicing and tilted dicing
- Quick changeover from perpendicular (0°) to any angle up to 15°
- Dedicated programmable work stations for both angular settings
- Field fine adjustment capability
- 0.1° angular repeatability
- 0.1° angular resolution
- Two preset angles:
  - First angle at 0°
  - Second angle at 0°-15°
  - Fine angle adjust capability

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	60K rpm / 1.8 kW or 2.2kW	
<b>Blade Size</b>	2" – 3"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Ø Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	965 x 1300 x 1600
	Weight	900 kg

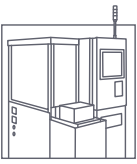
#### Materials:

##### Planar Wave Guides:

Silicon, Silica-on Silicon InP | Fiber Wave Guides | Fused Silica | Polymers on Si | GaAs | LiNbO3

##### Fiber Wave Guides:

SOI, SIO | LiNbO3 | Fused Silica



## UNIQUE SOLUTIONS

### 7100 XLA

For large PCB or RF devices



- Large dicing area up to 24" X 18"
- 2" or 4" configuration
- Easy access for maintenance
- Customization chucks, tape process with or without clamps
- Adjustable rotating monitor + USB hub

<b>Workpiece Size</b>	24" X 18"	
<b>Spindle</b>	60K rpm / 1.8 kW or 4" 30K rpm 2.5KW	
<b>Blade Size</b>	2"-3" or 4"-5"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	1670 x 1256 x 1600
	Weight	1000 kg

#### Materials:

Glass panels | PCB | FR4 + Copper | QFN and more

### 71MD

For ultrasound transducer

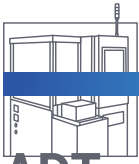


- Low-vibration spindle plus monitoring options
- Advanced height measurement capabilities
- Z linear Encoder
- Unique, Integrated balancing software
- PZT Wall Thickness Measurement

<b>Workpiece Size</b>	Ø 8"	
<b>Spindle</b>	60K rpm / 1.8 kW	
<b>Blade Size</b>	2" – 3"	
<b>Y Axis</b>	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Air Slide	
<b>Z Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>θ Axis</b>	Repeatability	4 arc-sec
	Stroke	380°
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
<b>Dimensions</b>	(W x D x H) mm	965 x 1300 x 1600
	Weight	900 kg

#### Materials:

Glass | PZT | LED & LED on PCB Packages | Sensors & MEMS | Opto-electronic Components | IC Wafers | Automotive Sensors | Ceramic Substrates & Capacitors | Glass on Silicon | LTCC | SAW Filters | Package Singulation (BGA, QFN)

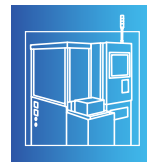


# ADT - Advanced Dicing Technologies



ADT is a one stop shop with end-to-end research, development and production, specializing in the development and manufacturing of **dicing saws, blades and peripherals** for a wide variety of applications: silicon- based ICs, Package Singulation and hard material Microelectronic Components (MEC). Our R&D department is known for combining deep technological know-how, vast experience and out-of-the-box solutions.

## Full Dicing Solutions



Saws



Blades



Peripherals

## ADT Worldwide

ADT offers a worldwide network of distributors, sales agents and independent representatives in Asia, USA and Europe, accompanied by a dedicated global service support team.

## Quality Standards

